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Substitute for form 1449A/B/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)				Complete If Known	
				Application Number	10/766,629 (Conf. No. 3771)
				Filing Date	January 27, 2004
				First Named Inventor	Glenn J. Leedy
				Art Unit	2818
				Examiner Name	Thinh T. Nguyen
Sheet	1	of	1	Attorney Docket Number	ELM-1 Cont.15

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number Number-Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
TH		US 3,932,932	01-20-1976	Goodman	
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PTO/SB/08a/b (08-03)

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		Svechnikov, S.V.; Kobylatskaya, M.F.; Kimarskii, V.I.; Kaufman, A.P.; Kuzovlev, Yu. I.; Cherepov, Ye. I.; Fomin, B.I.; "A switching plate with aluminum membrane crossings of conductors"; 1972	
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